Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	30	V
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current (Note 6) V_{GS} = 10V	T_C = +25°C T_C = +70°C	I_D	100 90	A
Continuous Drain Current (Note 5) V_{GS} = 10V	T_A = +25°C T_A = +70°C	I_D	22 18	A
Maximum Continuous Body Diode Forward Current (Note 5)		I_S	3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I_{DM}	100	A
Avalanche Current, L=1mH		I_{AS}	16	A
Avalanche Energy, L=1mH		E_{AS}	250	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	2.4	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	52	°C/W
Total Power Dissipation (Note 5)	T_C = +25°C	P_D	62	W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	2	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	V_{GS} = 0V, I_D = 1mA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 24V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = +20V, V_{DS} = 0V V_{GS} = -16V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	1	—	3	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	2.4	3.2	mΩ	V_{GS} = 10V, I_D = 20A
		—	4	5.5		V_{GS} = 4.5V, I_D = 15A
Diode Forward Voltage	V_{SD}	—	0.75	1	V	V_{GS} = 0V, I_S = 10A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{ISS}	—	2,370	—	pF	V_{DS} = 15V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{OSS}	—	1,360	—		
Reverse Transfer Capacitance	C_{RSS}	—	240	—		
Gate Resistance	R_G	—	0.6	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_G	—	20	—	nC	V_{DS} = 15V, I_D = 20A
Total Gate Charge (V_{GS} = 10V)	Q_G	—	44	—		
Gate-Source Charge	Q_{GS}	—	7	—		
Gate-Drain Charge	Q_{GD}	—	8	—		
Turn-On Delay Time	$t_{D(ON)}$	—	6.2	—	ns	V_{DD} = 15V, V_{GS} = 10V, R_L = 0.75Ω, R_G = 3Ω, I_D = 20A
Turn-On Rise Time	t_R	—	4.3	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	21	—		
Turn-Off Fall Time	t_F	—	8	—		
Bodyy Diode Reverse Recovery Time	t_{RR}	—	25	—	ns	I_F = 15A, di/dt = 500A/µs
Body Diode Reverse Recovery Charge	Q_{RR}	—	37	—	nC	

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
6. Thermal resistance from junction to soldering point (on the exposed drain pad).
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

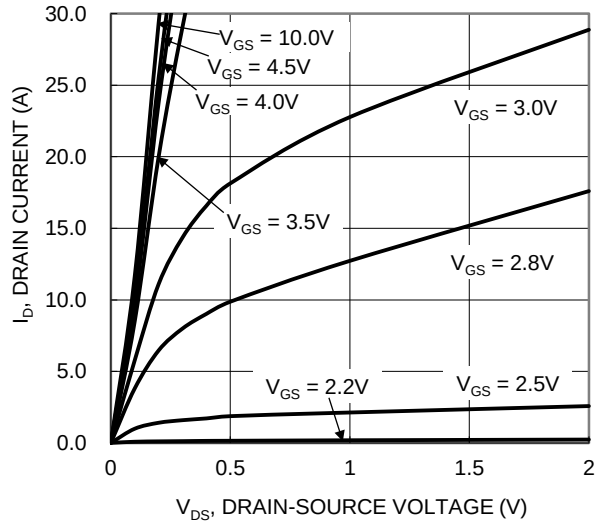


Figure 1. Typical Output Characteristic

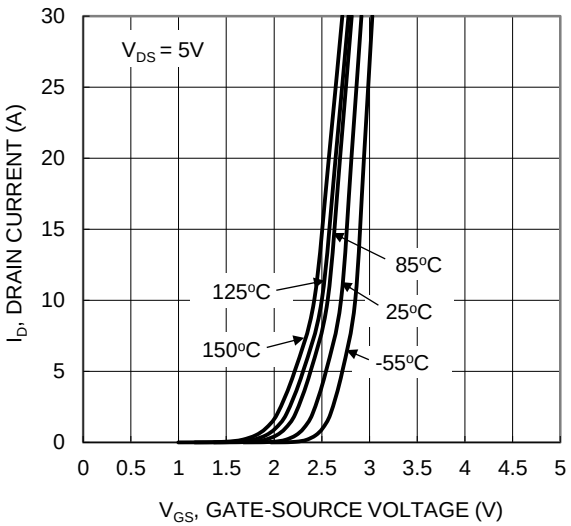


Figure 2. Typical Transfer Characteristic

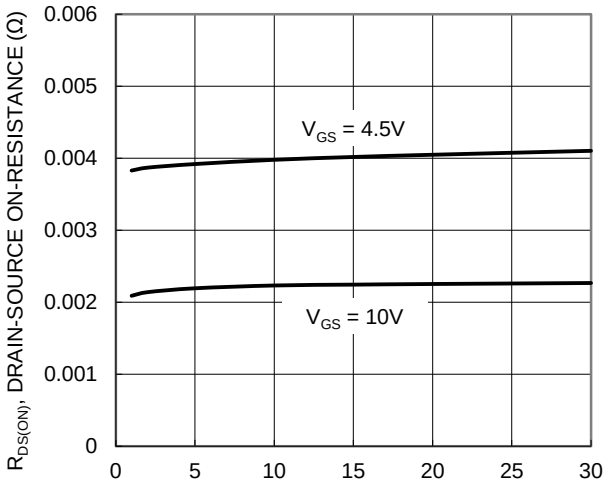


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

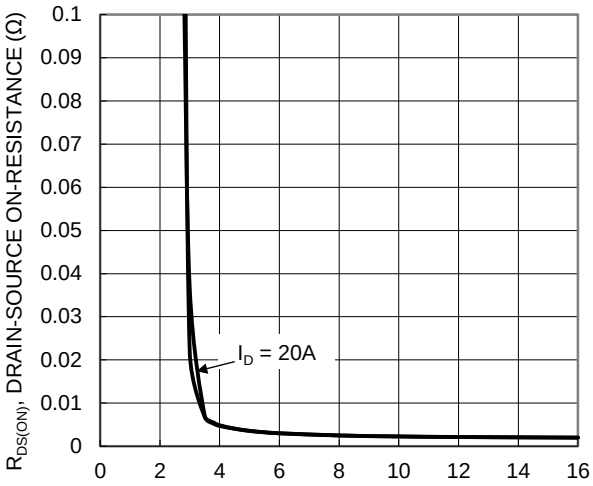


Figure 4. Typical Transfer Characteristic

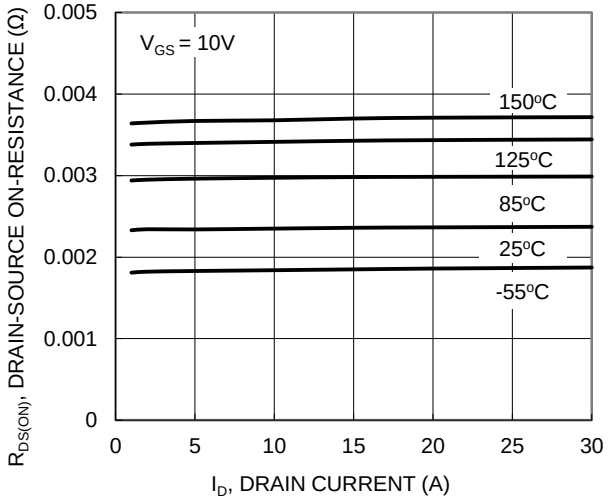


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

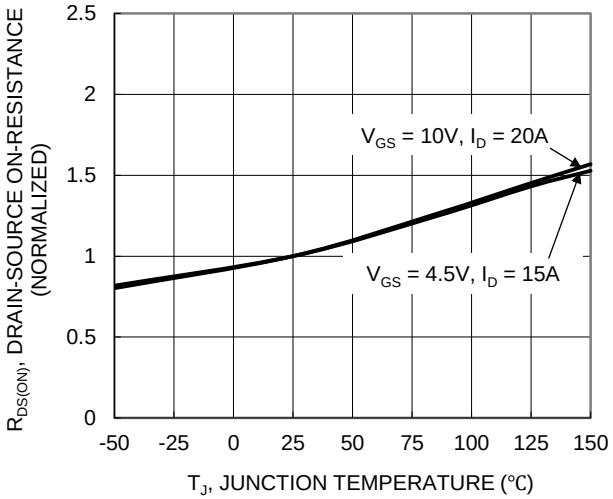


Figure 6. On-Resistance Variation with Junction Temperature

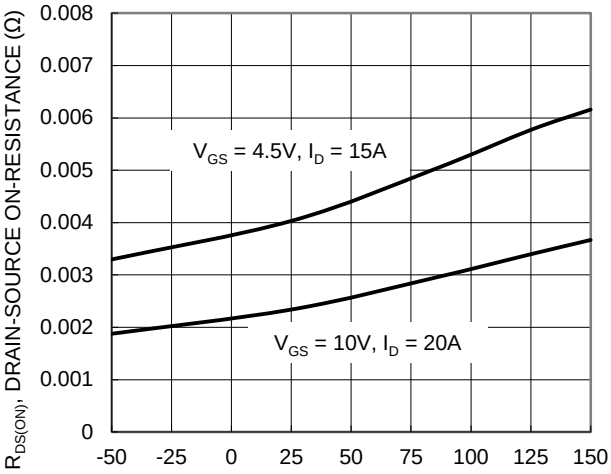


Figure 7. On-Resistance Variation with Junction Temperature

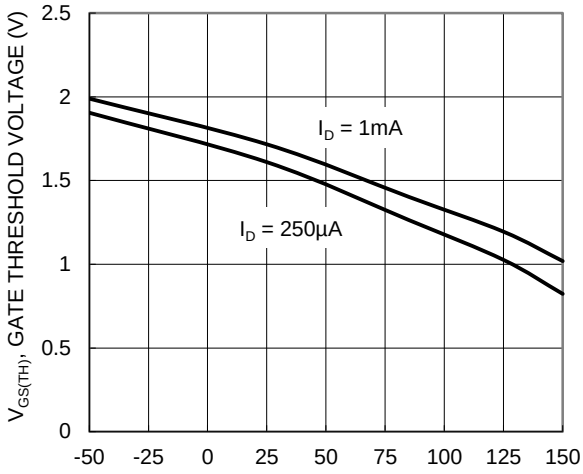


Figure 8. Gate Threshold Variation vs. Junction Temperature

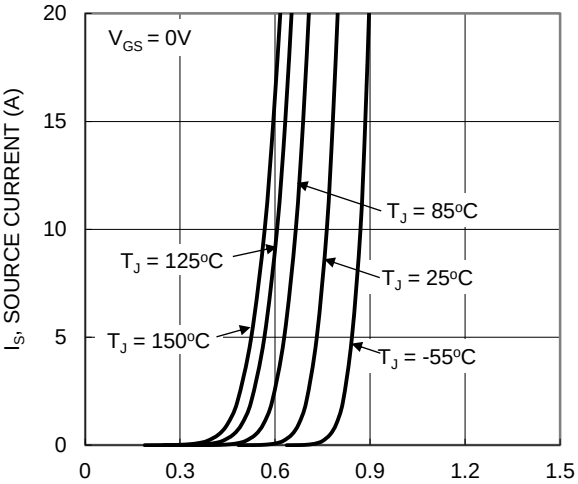


Figure 9. Diode Forward Voltage vs. Current

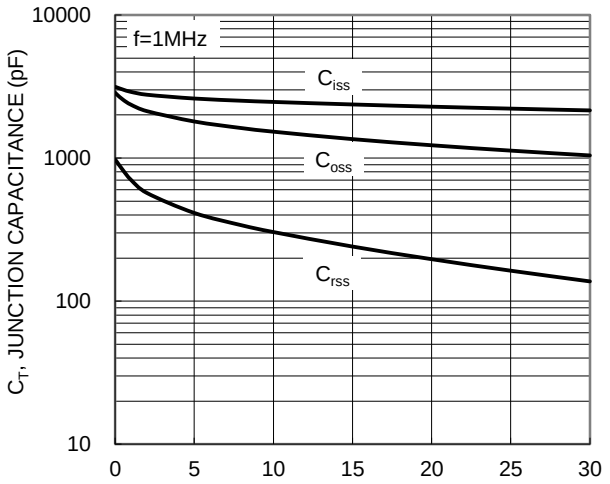


Figure 10. Typical Junction Capacitance

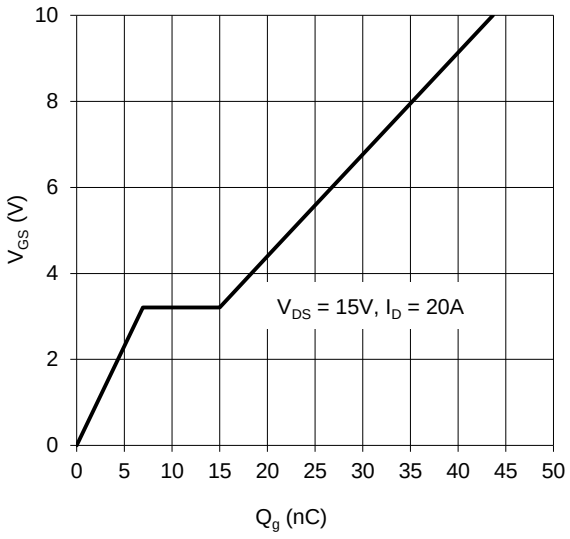


Figure 11. Gate Charge

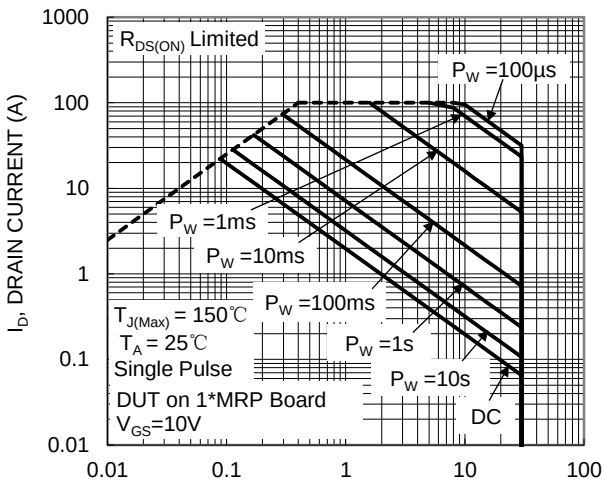


Figure 12. SOA, Safe Operation Area

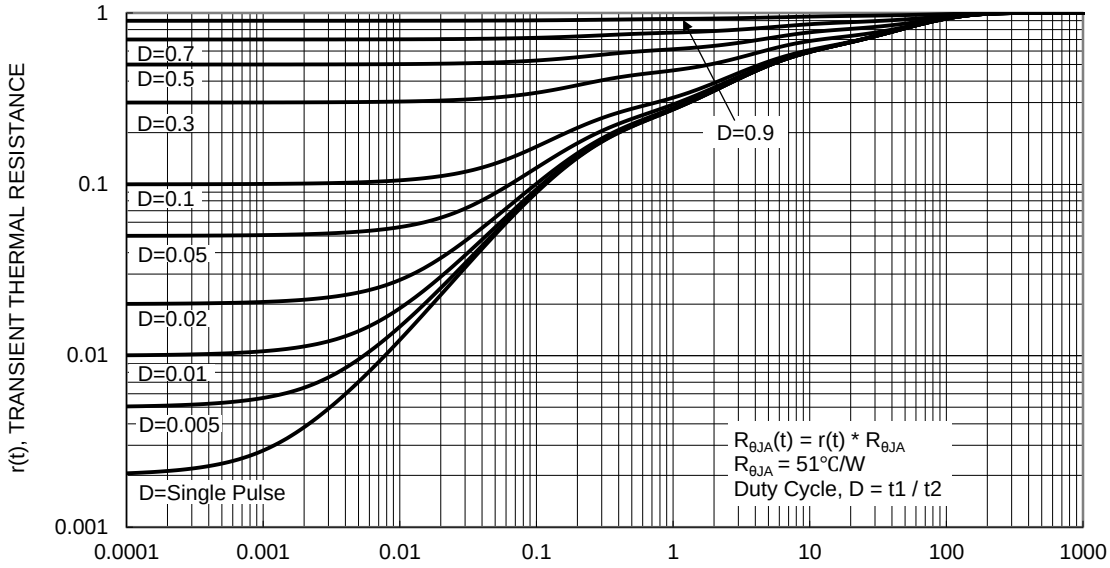
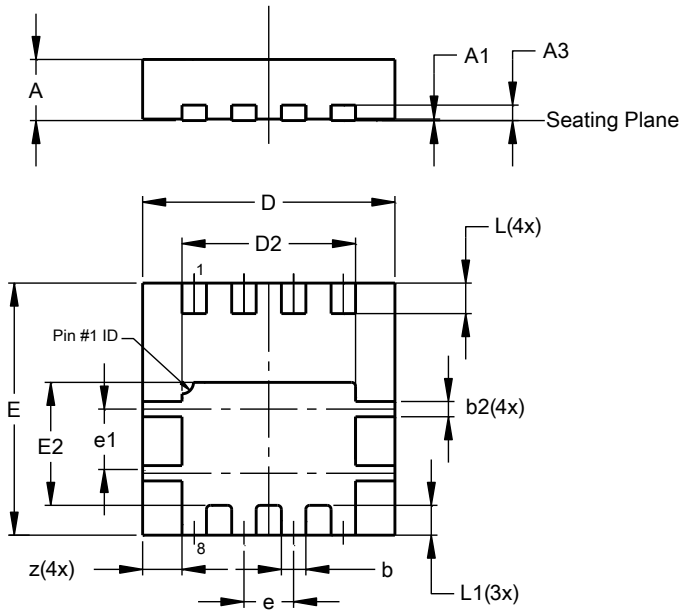


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8

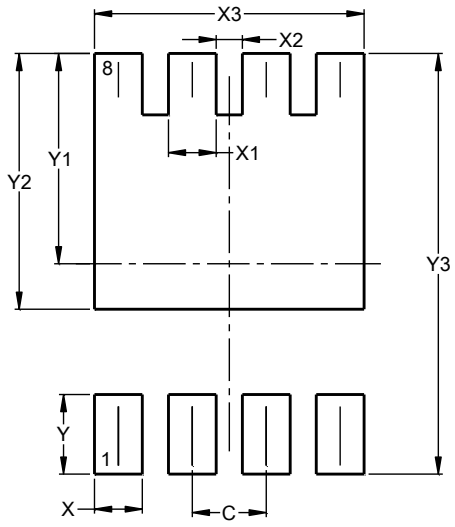


PowerDI3333-8			
Dim	**Min**	**Max**	**Typ**
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	–	–	0.203
b	0.27	0.37	0.32
b2	–	–	0.20
D	3.25	3.35	3.30
D2	2.22	2.32	2.27
E	3.25	3.35	3.30
E2	1.56	1.66	1.61
e	–	–	0.65
e1	0.79	0.89	0.84
L	0.35	0.45	0.40
L1	–	–	0.39
z	–	–	0.515
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700

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